

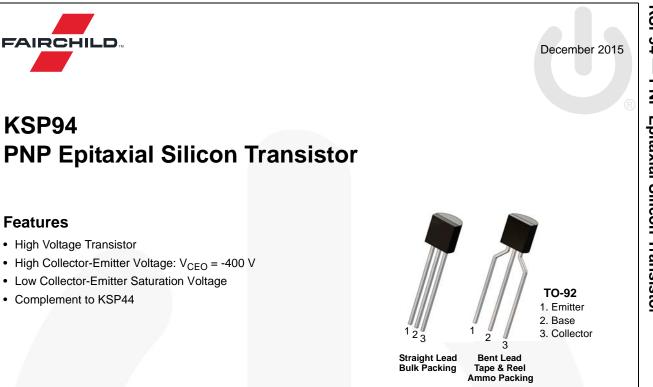
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#### **Ordering Information**

Part Number	Top Mark	Package	Packing Method
KSP94BU	KSP94	TO-92 3L	Bulk
KSP94TA	KSP94	TO-92 3L	Ammo

## **Absolute Maximum Ratings**

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only. Values are at  $T_A = 25^{\circ}$ C unless otherwise noted.

Symbol	Parameter	Value	Unit
V <sub>CBO</sub>	Collector-Base Voltage	-400	V
V <sub>CEO</sub>	Collector-Emitter Voltage	-400	V
V <sub>EBO</sub>	Emitter-Base Voltage	-6	V
۱ <sub>C</sub>	Collector Current	-300	mA
TJ	Junction Temperature	150	°C
T <sub>STG</sub>	Storage Temperature	-55 to +150	°C

## Thermal Characteristics<sup>(1)</sup>

Values are at  $T_A = 25^{\circ}C$  unless otherwise noted.

Symbol	Parameter	Max.	Unit
P <sub>D</sub>	Total Device Dissipation	625	mW
	Derate Above 25°C	5.0	mW/°C
R <sub>θJA</sub>	Thermal Resistance, Junction-to-Ambient	200	°C/W

Note:

1. PCB size: FR-4, 76 mm x 114 mm x 1.57 mm (3.0 inch x 4.5 inch x 0.062 inch) with minimum land pattern size.

#### **Electrical Characteristics**

Values are at  $T_A = 25^{\circ}C$  unless otherwise noted.

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV <sub>CBO</sub>	Collector-Base Breakdown Voltage	$I_{C} = -100 \ \mu A, \ I_{E} = 0$	-400			V
BV <sub>CEO</sub>	Collector-Emitter Breakdown Voltage	$I_{\rm C} = -1  {\rm mA},  I_{\rm B} = 0$	-400			V
BV <sub>EBO</sub>	Emitter-Base Breakdown Voltage	$I_{E} = -10 \ \mu A, \ I_{C} = 0$	-6			V
I <sub>CBO</sub>	Collector Cut-Off Current	$V_{CB} = -300 \text{ V}, I_{E} = 0$			-100	nA
I <sub>CES</sub>	Collector Cut-Off Current	$V_{CE} = -400 \text{ V}, \text{ V}_{BE} = 0$			-1	μΑ
I <sub>EBO</sub>	Emitter Cut-Off Current	$V_{EB} = -4 V, I_{C} = 0$			-100	nA
h <sub>FE</sub>	DC Current Gain	$V_{CE} = -10 \text{ V}, \text{ I}_{C} = -1 \text{ mA}$	40			
		$V_{CE} = -10 \text{ V}, \text{ I}_{C} = -10 \text{ mA}$	50		300	
		$V_{CE} = -10 \text{ V}, \text{ I}_{C} = -50 \text{ mA}$	45			
		$V_{CE} = -10 \text{ V}, \text{ I}_{C} = -100 \text{ mA}$	40			
V <sub>CE</sub> (sat)	Collector-Emitter Saturation Voltage	I <sub>C</sub> = -10 mA, I <sub>B</sub> = -1 mA			-500	mV
	Collector-Emilier Saturation voltage	I <sub>C</sub> = -50 mA, I <sub>B</sub> = -5 mA			-750	
V <sub>BE</sub> (sat)	Base-Emitter Saturation Voltage	I <sub>C</sub> = -10 mA, I <sub>B</sub> = -1 mA			-750	mV
C <sub>ob</sub>	Output Capacitance	$V_{CB} = -20 \text{ V}, I_E = 0,$ f = 1 MHz		7		pF

